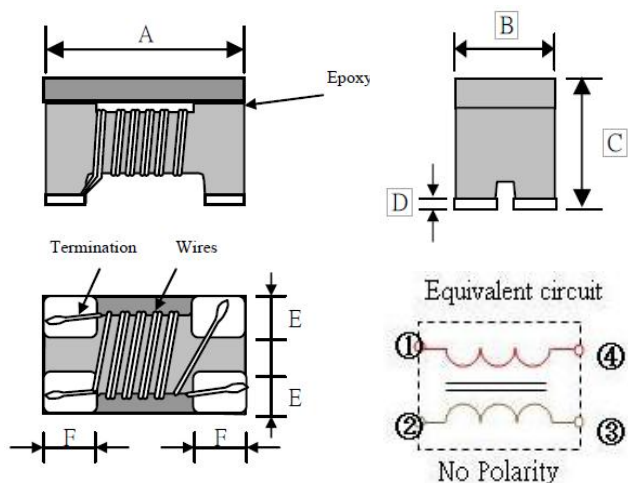


Common mode filter

◆ DIMENSIONS



A	2.5 ± 0.2
B	2.0 ± 0.2
C	1.8 ± 0.2
D	0.2 ± 0.1
E	0.4 ± 0.1
F	0.45 ± 0.1

◆ ELECTRICAL CHARACTERISTICS

P/N	Z (Ω)	DCR(Ω) (Max)	Idc(mA) (Max)	Rated Voltage	Insulation Resistance
	Common mode			VDC	IR
	Impedance			(V)Typical	(MΩ) Min
	At° 100MHz				
SMW2520S301ATT	250min (300Typ)	0.35	400	20	10
SMW2520S601ATT	450min (600Typ)	0.45	300	20	10
SMW2520S102ATT	750min (1000Typ)	0.9	200	20	10

Operating temperature : -25 to +85°C

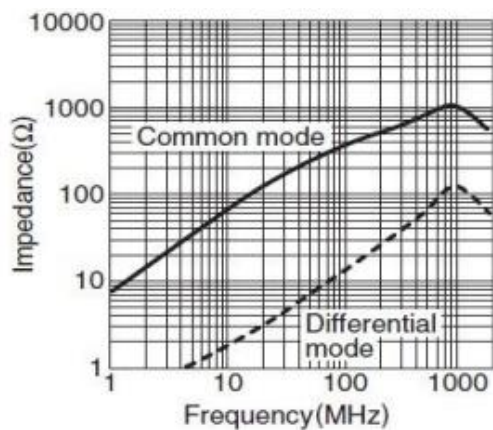
Storage temp and humidity : -40 to +85°C , 70%RH max

Typical Heat Rating DC Current would cause an approximately ΔT of 40°C

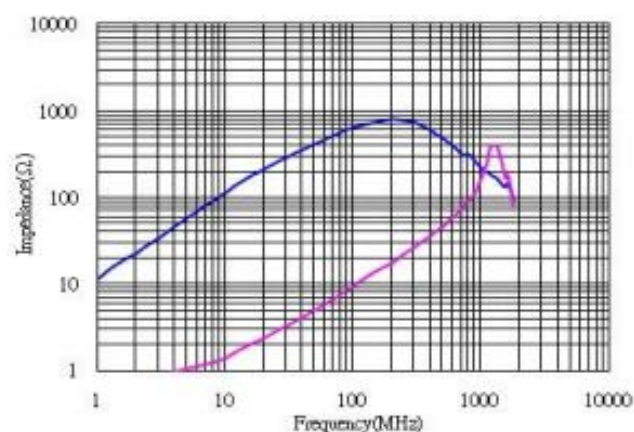
If Use Wave soldering is there will be some risk. Re-flow soldering temperatures below 240 degrees, there will be unwitting risk

◆ PERFORMANCE CURVES

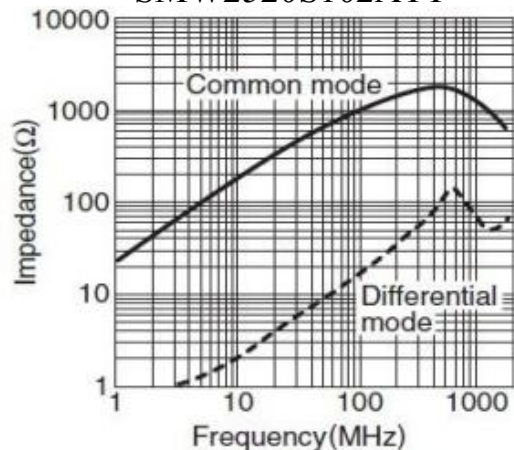
SMW2520S301ATT



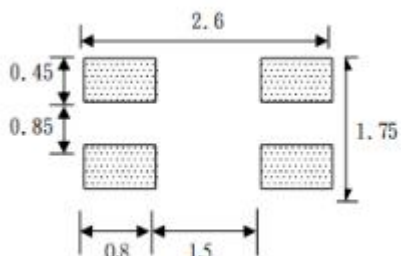
SMW2520S601ATT



SMW2520S102ATT



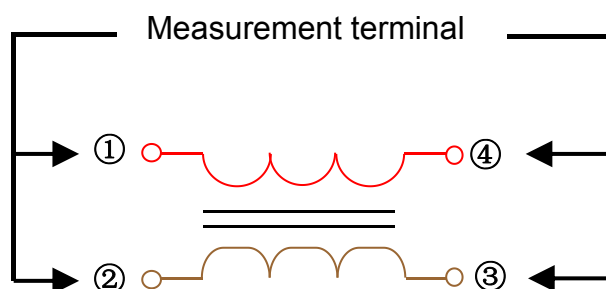
Recommended Soldering Conditions (Please use this product by reflow soldering)
Recommended Footprint(mm)



◆ Test Equipment

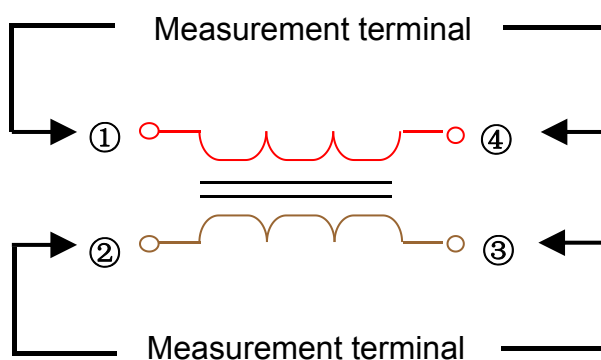
Impedance / Inductance

Measured by using Agilent 4291A RF Impedance Analyzer.



DC Resistance

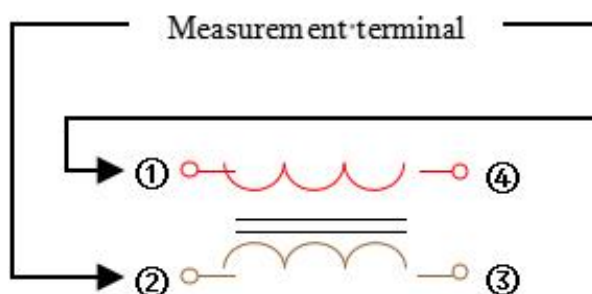
Measured by using Chroma 4338 mill ohm meter.



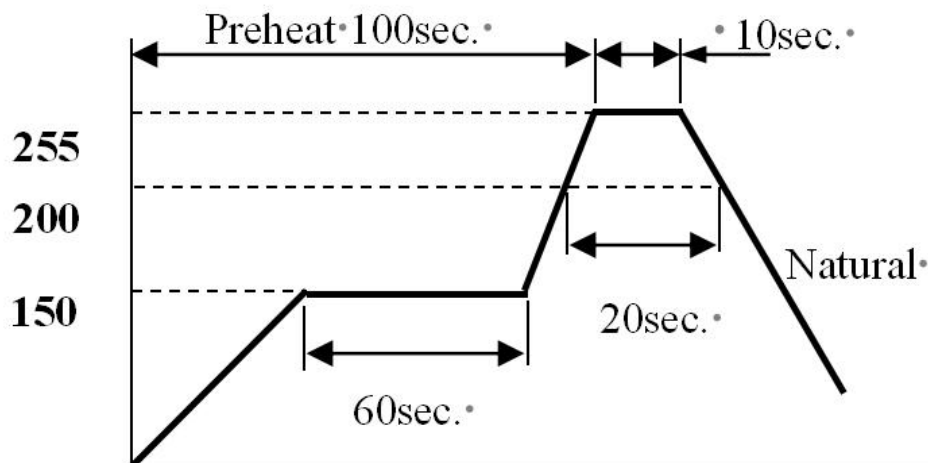
Insulation Resistance

Measured by using Chroma 19073

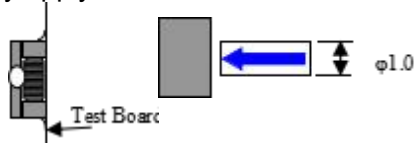
Measurement voltage : 50v , Measurement time : 60 sec



◆ RECOMMENDED SOLDERING TEMP. GRAPH



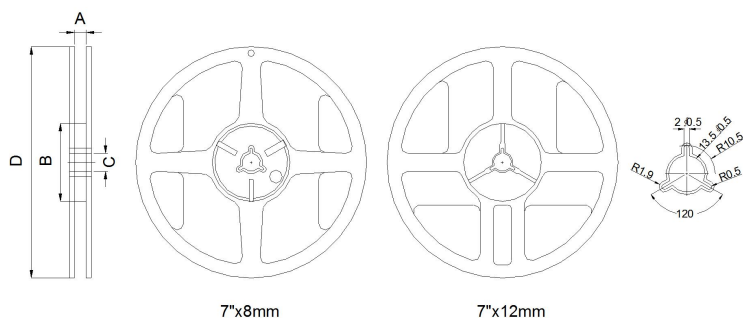
◆ MECHANICAL RELIABILITY

TEST	Specification & Requirement		Method Used
Solderability	The surface of terminal/pin tested shall be covered with new solder by 90%		Solder heat proof: Preheating: $150 \pm 10^{\circ}\text{C}$ 60 seconds Soldering: $245 \pm 5^{\circ}\text{C}$ for 4 ± 1 sec
Solder Heat Resistance	Components should have not evidence of electrical and mechanical damage Impedance: within $\pm 15\%$ of initial value		Preheating: 150°C 60secs Solder temperature: $260 \pm 5^{\circ}\text{C}$ Flux: rosin Dip time: 10 ± 0.5 secs
Terminal strength	Series No.	F (Kg)	Solder a chip to test substrate and then laterally apply a force in the arrow direction 
	1608	0.5	
	2012	0.5	
	2520	0.5	
	3216	1.0	

◆ ENDURANCE RELIABILITY

TEST	Specification & Requirement	Method Used
Thermal Shock	Impedance change within $\pm 15\%$ Without mechanical damage	-65°C , (30 mins) \rightarrow room temp. (2 mins) - $> 125^{\circ}\text{C}$, (30 mins) \rightarrow room temp. (2 mins) 50 cycles
Humidity Resistance	Impedance change within $\pm 15\%$ Without mechanical damage	Apply IDC current @ 60°C ambient Humidity: 90% Duration: 168 hrs
Low Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $-40 \pm 2^{\circ}\text{C}$ for total 168 ± 0 hours
High Temp. Storing	Impedance change within $\pm 15\%$ Without mechanical damage	Storing Temp. $125 \pm 2^{\circ}\text{C}$ for total 168 ± 0 hours

◆ Reel Dimension & Tape Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)	Packaging Quantity
7"x8mm	9.0±0.5	60±2	13.5±0.5	178±2	2000
7"x12mm	13.5±0.5	60±2	13.5±0.5	178±2	2000